

4 layers FPC 35µm - stack-up "thick"

Layer	Description	Stack-up	Thickness	Type
	solder mask		10 µm	wet Solder Mask
Top L1	Copper		35 µm	Cu
	Glue		20 µm	epoxy
	Polyimid		25 µm	PI
	Glue		20 µm	epoxy
IL2	Copper		35 µm	Cu
	Glue		20 µm	epoxy
IL3	Copper		35 µm	Cu
	Glue		20 µm	epoxy
	Polyimid		25 µm	PI
	Glue		20 µm	epoxy
Bot L4	Copper		35 µm	Cu
	Glue		20 µm	epoxy
	Stiffener*		1200 µm	FR4

total thickness incl. stiffener:	1,520 mm
total thickness excl. stiffener:	0,320 mm
tolerance	10%
maximum thickness	1,672 mm
minimum thickness	1,368 mm

* The stiffener is optional and may cover only different parts of the FPC.
Different thicknesses are available. Polyimide stiffeners are possible too.

4 layers FPC 35µm - stack-up "thin"

Layer	Description	Stack-up	Thickness	Type
	solder mask		10 µm	wet Solder Mask
Top L1	Copper		35 µm	Cu
	Glue		12,7 µm	epoxy
	Polyimid		12,7 µm	PI
	Glue		12,7 µm	epoxy
IL2	Copper		35 µm	Cu
	Glue		12,7 µm	epoxy
IL3	Copper		35 µm	Cu
	Glue		12,7 µm	epoxy
	Polyimid		12,7 µm	PI
	Glue		12,7 µm	epoxy
Bot L4	Copper		35 µm	Cu
	Glue		12,7 µm	epoxy
	Stiffener*		1200 µm	FR4
			total thickness incl. stiffener:	1,452 mm
			total thickness excl. stiffener:	0,252 mm
			tolerance	10%
			maximum thickness	1,597 mm
			minimum thickness	1,306 mm

* The stiffener is optional and may cover only different parts of the FPC.
Different thicknesses are available. Polyimide stiffeners are possible too.